SPECIFICATION
FOR
EPD Module

MODULE No:	KD027QVFSN008
CUSTOMER:	

STARTEK	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		

Revision History

Date	Rev. No.	Page	Summary
2023.07.07	V1.0	ALL	FIRST ISSUE

Contents

1. Over View

KD027QVFSN008 is an Active Matrix Electrophoretic Display (AMEPD), with interface and a reference system design. The 2.66" active area contains 152×296 pixels, and has 1-bit B/W/R full display cap abilities. An integrated circuit contains gate buffer, source buffer, interface, timing control logic, oscillator, DC-DC, SRAM, LUT, VCOM
and border are supplied with each panel.

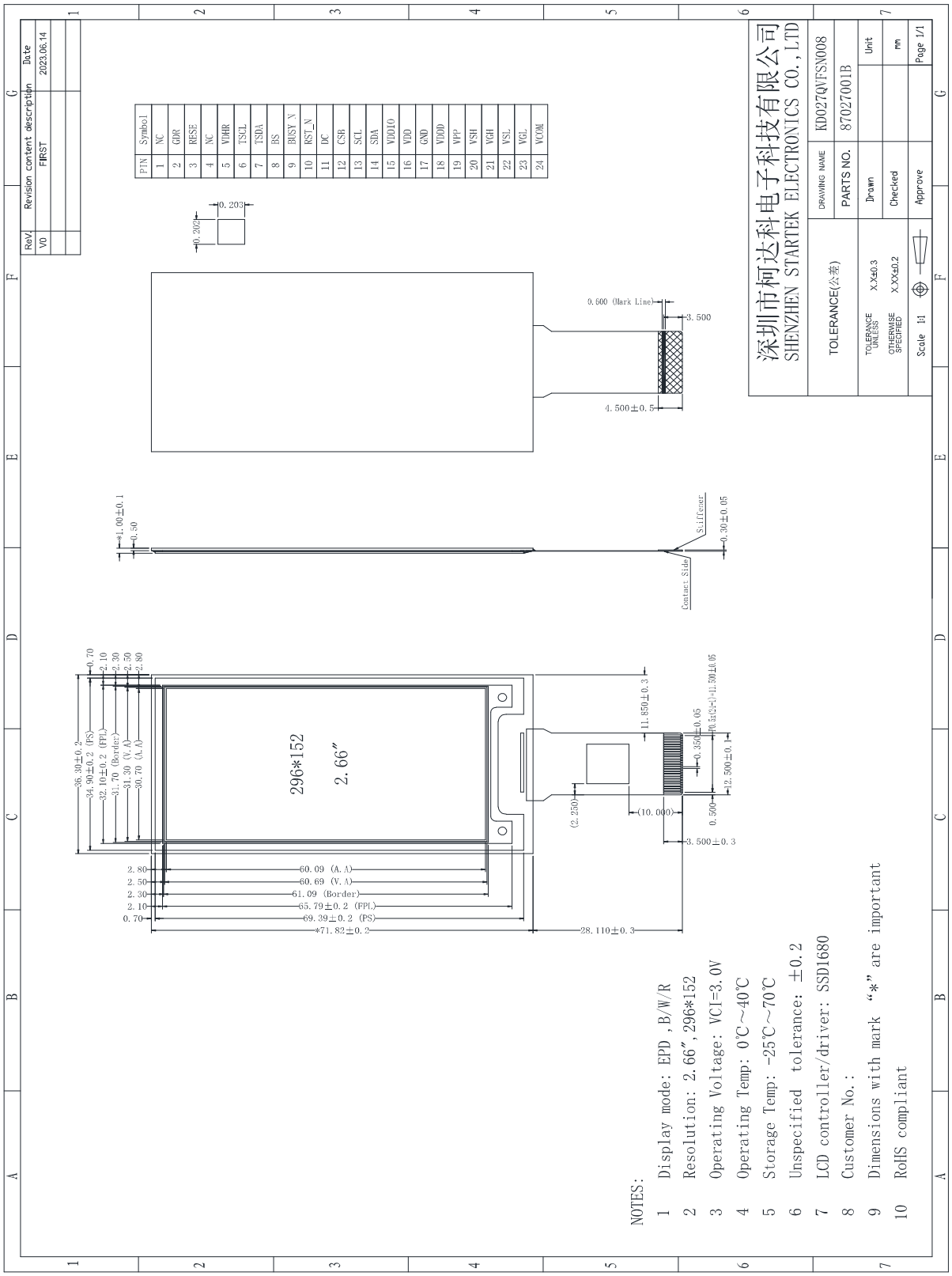
2. Features

- 296×152 pixels display
- High contrast High reflectance
- Ultra wide viewing angle Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Commercial temperature range
- Landscape portrait modes
- Hard-coat antiglare display surface
- Ultra Low current deep sleep mode
- On chip display RAM
- Low voltage detect for supply voltage
- High voltage ready detect for driving voltage
- Internal temperature sensor
- 10-byte OTP space for module identification
- Waveform can stored in On-chip OTP
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I²C signal master interface to read external temperature sensor

3. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	2.66	Inch	
Display Resolution	152(H) x 296(V)	Pixel	
Active Area	30.70(H) x 60.09(V)	mm	
Pixel pitch	0.202(H) x 0.203(V)	mm	
Pixel Configuration	Rectangle		
Outline Dimension	36.3(H) x 71.82(V) x 0.9(D)	mm	
Module Weight	5	g	
Controller IC	SSD1680		
Interface	3Wire / 4Wire SPI	-	
Display mode	EPD,B / W / R	-	
Operating temperature	0～+40	℃	
Storage temperature	-25～+70	℃	

4. Mechanical Drawing of EPD module



5. Input/Output Pin Assignment

NO.	Name	DISCRIPTION	I/O	Remark
1	NC	NO Connection	-	Keep open
2	GDR	N-Channel MOSFET Gate Drive Control	O	
3	RESE	Current Sense Input for the Control Loop	I	
4	NC	NO Connection	-	Keep open
5	VSH2	Positive Source driving voltage(Red)	C	
6	TSCL	IIC Interface to digital temperature sensor Clock pin	O	
7	TSDA	IIC Interface to digital temperature sensor Data pin	I/O	
8	BS1	Bus Interface selection pin	I	Note 5-5
9	BUSY	Busy state output pin	O	Note 5-4
10	RES#	Reset signal input. Active Low.	I	Note 5-3
11	D/C#	Data /Command control pin	I	Note 5-2
12	CS#	Chip select input pin	I	Note 5-1
13	SCL	Serial Clock pin (SPI)	I	
14	SDA	Serial Data pin (SPI)	I/O	
15	VDDIO	Power Supply for interface logic pins It should be connected with VCI	P	
16	VCI	Power Supply for the chip	P	
17	VSS	Ground	P	
18	VDD	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS	C	
19	VPP	FOR TEST	P	
20	VSH1	Positive Source driving voltage	C	
21	VGH	Power Supply pin for Positive Gate driving voltage and VSH1	C	
22	VSL	Negative Source driving voltage	C	
23	VGL	Power Supply pin for Negative Gate driving voltage VCOM and VSL	C	
24	VCOM	VCOM driving voltage	C	

I = Input Pin, O =Output Pin, I/O = Bi-directional Pin (Input/output),
P = Power Pin, C =Capacitor Pin

Note 5-1: This pin (CS#) is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled Low.

Note 5-2: This pin (D/C#) is Data/Command control pin connecting to the MCU in 4 -wire SPI mode. When the pin is pulled High, the data at SDA will be interpreted as data. When the pin is pulled Low, the data at SDA will be interpreted as command.

Note 5-3: This pin (RES#) is reset signal input. The Reset is active low.

Note 5-4: This pin is Busy state output pin. When Busy is High, the operation of chip should not be interrupted, command should not be sent. The chip would put Busy pin High when -Outputting display waveform -Communicating with digital temperature sensor.

Note 5-5: This pin (BS1) is for 3-line SPI or 4-line SPI selection. When it is "Low", 4-line SPI is selected. When it is "High", 3-line SPI (9 bits SPI) is selected. Please refer to below Table.

BS1 State	MCU Interface
L	4-lines serial peripheral interface(SPI) - 8 bits SPI
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

6. Electrical Characteristics

6.1 Absolute Maximum Rating

Parameter	Symbol	Rating	Unit
Logic supply voltage	VCI	-0.5 to +6.0	V
Logic Input voltage	VIN	-0.5 to VCI+0.5	V
Logic Output voltage	VOUT	-0.5 to VCI+0.5	V
Operating Temp range	TOPR	0 to +40	°C
Storage Temp range	TSTG	-25 to+60	°C

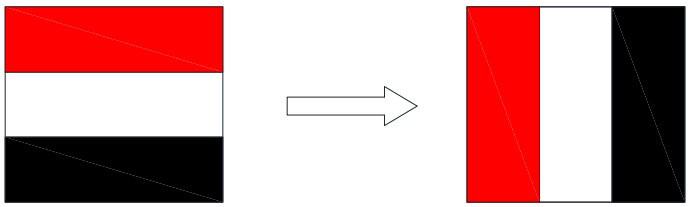
Note: Maximum ratings are those values beyond which damages to the device may occur.
Functional operation should be restricted to the limits in the Panel DC Characteristics tables.

6.2 Panel DC Characteristics

The following specifications apply for: VSS=0V, VCI=3.0V, TOPR =23ºC

Parameter	Symbol	Conditions	Applicable pin	Min.	Typ.	Max	Units
Single ground	VSS	-		-	0	-	V
Logic supply voltage	VCI	-	VCI	2.5	3.0	3.7	V
Core logic voltage	VDD		VDD	1.7	1.8	1.9	V
High level input voltage	VIH	-	-	0.8 VCI	-	-	V
Low level input voltage	VIL	-	-	-	-	0.2VCI	V
High level output voltage	VOH	IOH = -100uA	-	0.9 VCI	-	-	V
Low level output voltage	VOL	IOL = 100uA	-	-	-	0.1VCI	V
Typical power	PTYP	VCI =3.0V	-	-	12.9	-	mW
Deep sleep mode	PSTPY	VCI =3.0V	-	-	0.003	-	mW
Typical operating current	Iopr_VCI	VCI =3.0V	-	-	3	-	mA
Image update time	-	25 ºC	-	-	-		sec
Sleep mode current	Islp_VCI	DC/DC off No clock No input load Ram data retain	-	-	-	-	uA
Deep sleep mode current	Idslp_VCI	DC/DC off No clock No input load Ram data not retain	-	-	-	3	uA

Notes:1.The typical power consumption is measured with following pattern transition: from horizontal 3 gray scale pattern to vertical 3 gray scale pattern.



2.The deep sleep power is the consumed power when the panel controller is in deep sleep mode.

3.The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by SID.

6.3 AC Characteristics

6.3.1 MCU Interface selection

The pin assignment at different interface mode is summarized in Table.Different MCU mode can be set by hardware selection on BS1 pins.The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

Pin Name	Data/Command Interface		Control Signal		
Bus interface	SDA	SCL	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDA	SCL	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDA	SCL	CS#	L	RES#

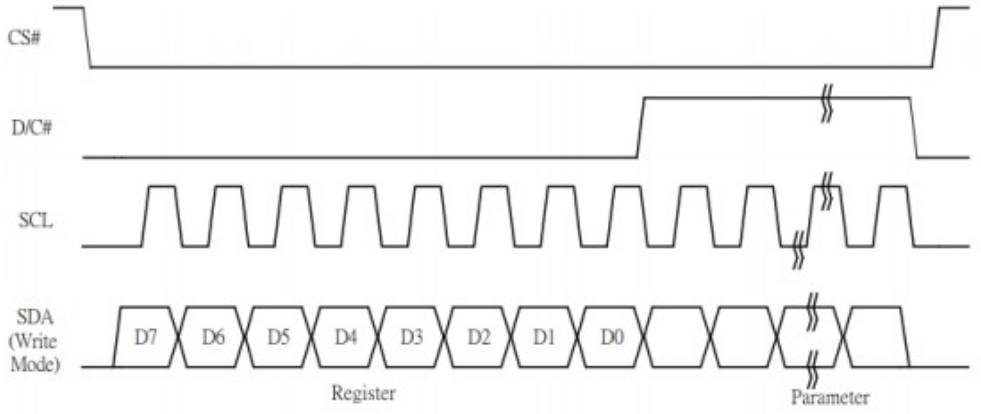
6.3.2 MCU Serial Interface (4-wire SPI)

The 4-wire SPI consists of serial clock SCL, serial data SDA, D/C# and CS#.
This interface supports Write mode and Read mode.

Function	CS#	D/C#	SCL
Write command	L	L	↑
Write data	L	H	↑

Note:
(1) ↑ stands for rising edge of signal

In the write mode SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7, D6, ... D0. The level of D/C# should be kept over the whole byte. The data byte in the shift register is written to the Graphic Display Data RAM (RAM)/Data Byte register or command Byte register according to D/C# pin.



Write procedure in 4-wire SPI mode

In the Read mode:

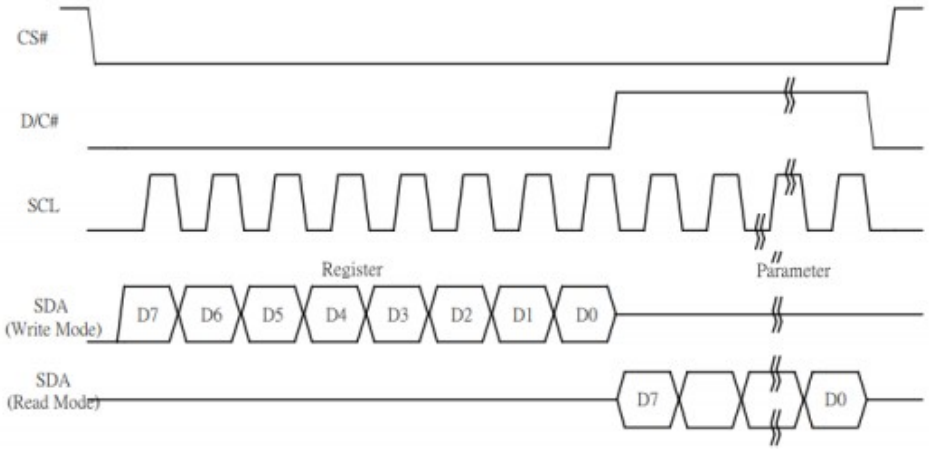
1.After driving CS# to low, MCU need to define the register to be read.

2.SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7,D6,...D0 With D/C# keep low.

3.After SCL change to low for the last bit of register, D/C# need to drive to high.

4.SDA is shifted out an 8-bit data on every falling edge of SCL in the order of D7,D6,…D0.

5.Depending on register type, more than 1 byte can be read out. After all byte are read, CS# need to drive to high to stop the read operation.



read procedure in 4-wire SPI mode

6.3.3 MCU Serial Interface (3-wire SPI)

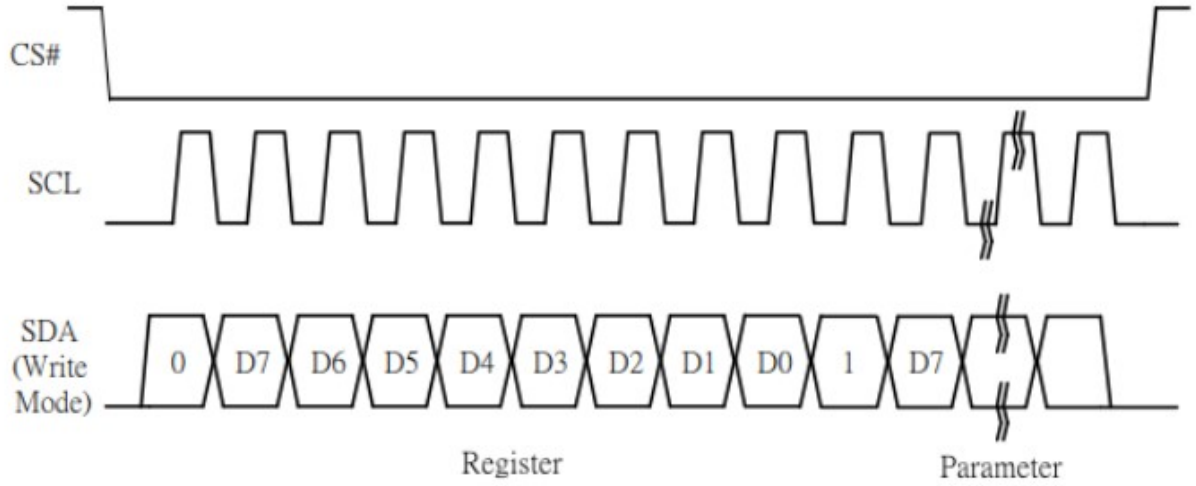
The 3-wire SPI consists of serial clock SCL, serial data SDA and CS#.

This interface also supports Write mode and Read mode.

The operation is similar to 4-wire serial interface while D/C# pin is not used.There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence:D/C#bit,D7 to D0 bit.The D/C# bit(first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

Function	CS#	D/C#	SCL
Write command	L	Tie	↑
Write data	L	Tie	↑

Note: ↑ stands for rising edge of signal



Write procedure in 3-wire SPI mode

In the Read mode:

1.After driving CS# to low, MCU need to define the register to be read.

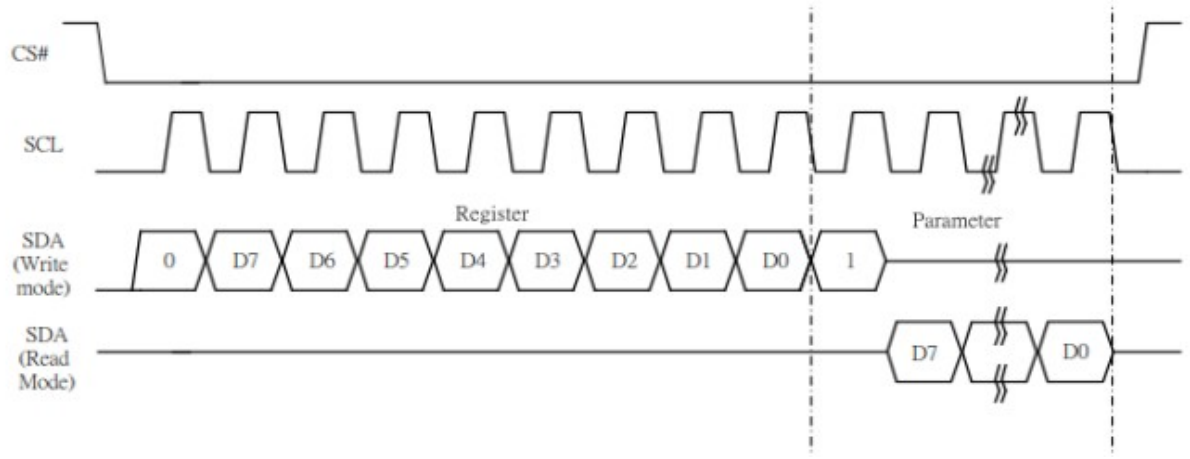
2.D/C=0 is shifted thru SDA with one rising edge of SCL.

3.SDA is shifted into an 8-bit shift register on every rising edge of SCL in the order of D7,D6,...D0.

4.D/C=1 is shifted thru SDA with one rising edge of SCL

5.SDA is shifted out an 8-bit data one very falling edge of SCL in the order of D7,D6,…D0.

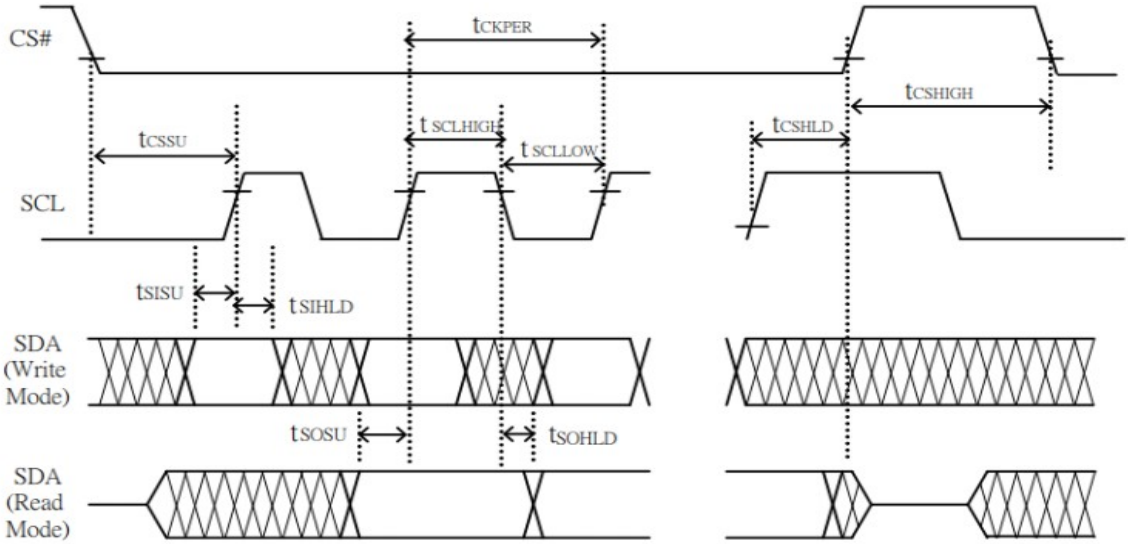
6.Depending on register type, more than 1 byte can be read out. After all byte are read,CS# need to drive to high to stop the read operation.



Read procedure in 3-wire SPI mode

6.3.4 Interface Timing

The following specifications apply for:VSS=0V, VCI=3.0V, TOPR=25ºC



Write mode

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL frequency (Write Mode)	-	-	20	MHz
t_{CSSU}	Time CS# has to be low before the first rising edge of SCLK	60	-	-	ns
t_{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	65	-	-	ns
t_{CSHIGH}	Time CS# has to remain high between two transfers	100	-	-	ns
$t_{SCLHIGH}$	Part of the clock period where SCL has to remain high	25	-	-	ns
t_{SCLLOW}	Part of the clock period where SCL has to remain low	25	-	-	ns
t_{SISU}	Time SI (SDA Write Mode) has to be stable before the next rising edge of SCL	10	-	-	ns
t_{SIHLD}	Time SI (SDA Write Mode) has to remain stable after the rising edge of SCL	40	-	-	ns

Read mode

Symbol	Parameter	Min	Typ	Max	Unit
f_{SCL}	SCL frequency (Read Mode)	-	-	2.5	MHz
t_{CSSU}	Time CS# has to be low before the first rising edge of SCLK	100	-	-	ns
t_{CSHLD}	Time CS# has to remain low after the last falling edge of SCLK	50	-	-	ns
t_{CSHIGH}	Time CS# has to remain high between two transfers	250	-	-	ns
$t_{SCLHIGH}$	Part of the clock period where SCL has to remain high	180	-	-	ns
t_{SCLLOW}	Part of the clock period where SCL has to remain low	180	-	-	ns
t_{SOSU}	Time SO(SDA Read Mode) will be stable before the next rising edge of SCL	-	50	-	ns
t_{SOHLD}	Time SO (SDA Read Mode) will remain stable after the falling edge of SCL	-	0	-	ns

7. Command Table

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting A[8:0]= 127h [POR], 296 MUX MUX Gate lines setting as (A[8:0] + 1). B[2:0] = 000 [POR]. Gate scanning sequence and direction B[2]: GD Selects the 1st output Gate GD=0 [POR], G0 is the 1st gate output channel, gate output sequence is G0,G1, G2, G3, ... GD=1, G1 is the 1st gate output channel, gate output sequence is G1, G0, G3, G2, ... B[1]: SM Change scanning order of gate driver. SM=0 [POR], G0, G1, G2, G3...295 (left and right gate interlaced) SM=1, G0, G2, G4 ...G294, G1, G3, ...G295 B[0]: TB TB = 0 [POR], scan from G0 to G295 TB = 1, scan from G295 to G0.
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	0	0	0	0	0	A_8		
0	1		0	0	0	0	0	B_2	B_1	B_0		
0	0	03	0	0	0	0	0	0	1	1	Gate Driving voltage Control	Set Gate driving voltage A[4:0] = 00h [POR] VGH setting from 10V to 20V
0	1		0	0	0	A_4	A_3	A_2	A_1	A_0		

A[4:0]	VGH	A[4:0]	VGH
00h	20	0Dh	15
03h	10	0Eh	15.5
04h	10.5	0Fh	16
05h	11	10h	16.5
06h	11.5	11h	17
07h	12	12h	17.5
08h	12.5	13h	18
07h	12	14h	18.5
08h	12.5	15h	19
09h	13	16h	19.5
0Ah	13.5	17h	20
0Bh	14	Other	NA
0Ch	14.5		

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	04	0	0	0	0	0	1	0	0	Source Driving voltage Control	Set Source driving voltage A[7:0] = 41h [POR], VSH1 at 15V B[7:0] = A8h [POR], VSH2 at 5V. C[7:0] = 32h [POR], VSL at -15V Remark: VSH1>=VSH2
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		

A[7]/B[7] = 1,
VSH1/VSH2 voltage setting from 2.4V to 8.8V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
8Eh	2.4	AFh	5.7
8Fh	2.5	B0h	5.8
90h	2.6	B1h	5.9
91h	2.7	B2h	6
92h	2.8	B3h	6.1
93h	2.9	B4h	6.2
94h	3	B5h	6.3
95h	3.1	B6h	6.4
96h	3.2	B7h	6.5
97h	3.3	B8h	6.6
98h	3.4	B9h	6.7
99h	3.5	BAh	6.8
9Ah	3.6	BBh	6.9
9Bh	3.7	BCh	7
9Ch	3.8	BDh	7.1
9Dh	3.9	BEh	7.2
9Eh	4	BFh	7.3
9Fh	4.1	C0h	7.4
A0h	4.2	C1h	7.5
A1h	4.3	C2h	7.6
A2h	4.4	C3h	7.7
A3h	4.5	C4h	7.8
A4h	4.6	C5h	7.9
A5h	4.7	C6h	8
A6h	4.8	C7h	8.1
A7h	4.9	C8h	8.2
A8h	5	C9h	8.3
A9h	5.1	CAh	8.4
AAh	5.2	CBh	8.5
ABh	5.3	CCh	8.6
ACh	5.4	CDh	8.7
ADh	5.5	CEh	8.8
AEh	5.6	Other	NA

A[7]/B[7] = 0,
VSH1/VSH2 voltage setting from 9V to 17V

A/B[7:0]	VSH1/VSH2	A/B[7:0]	VSH1/VSH2
23h	9	3Ch	14
24h	9.2	3Dh	14.2
25h	9.4	3Eh	14.4
26h	9.6	3Fh	14.6
27h	9.8	40h	14.8
28h	10	41h	15
29h	10.2	42h	15.2
2Ah	10.4	43h	15.4
2Bh	10.6	44h	15.6
2Ch	10.8	45h	15.8
2Dh	11	46h	16
2Eh	11.2	47h	16.2
2Fh	11.4	48h	16.4
30h	11.6	49h	16.6
31h	11.8	4Ah	16.8
32h	12	4Bh	17
33h	12.2	Other	NA
34h	12.4		
35h	12.6		
36h	12.8		
37h	13		
38h	13.2		
39h	13.4		
3Ah	13.6		
3Bh	13.8		

C[7] = 0,
VSL setting from -5V to -17V

C[7:0]	VSL
0Ah	-5
0Ch	-5.5
0Eh	-6
10h	-6.5
12h	-7
14h	-7.5
16h	-8
18h	-8.5
1Ah	-9
1Ch	-9.5
1Eh	-10
20h	-10.5
22h	-11
24h	-11.5
26h	-12
28h	-12.5
2Ah	-13
2Ch	-13.5
2Eh	-14
30h	-14.5
32h	-15
34h	-15.5
36h	-16
38h	-16.5
3Ah	-17
Other	NA

0	0	08	0	0	0	0	1	0	0	0	Initial Code Setting OTP Program	Program Initial Code Setting The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	09	0	0	0	0	1	0	0	1	Write Register for Initial Code Setting	Write Register for Initial Code Setting Selection A[7:0] ~ D[7:0]: Reserved Details refer to Application Notes of Initial Code Setting
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
0	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
0	0	0A	0	0	0	0	1	0	1	0	Read Register for Initial Code Setting	Read Register for Initial Code Setting

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	0C	0	0	0	0	1	1	0	0	Booster Soft start Control	Booster Enable with Phase 1, Phase 2 and Phase 3 for soft start current and duration setting.
0	1		1	A_6	A_5	A_4	A_3	A_2	A_1	A_0		A[7:0] -> Soft start setting for Phase1 = 8Bh [POR]
0	1		1	B_6	B_5	B_4	B_3	B_2	B_1	B_0		B[7:0] -> Soft start setting for Phase2 = 9Ch [POR]
0	1		1	C_6	C_5	C_4	C_3	C_2	C_1	C_0		C[7:0] -> Soft start setting for Phase3 = 96h [POR]
0	1		0	0	D_5	D_4	D_3	D_2	D_1	D_0		D[7:0] -> Duration setting = 0Fh [POR]

Bit Description of each byte:
A[6:0] / B[6:0] / C[6:0]:

Bit[6:4]	Driving Strength Selection
000	1(Weakest)
001	2
010	3
011	4
100	5
101	6
110	7
111	8(Strongest)

Bit[3:0]	Min Off Time Setting of GDR [Time unit]
0000 ~ 0011	NA
0100	2.6
0101	3.2
0110	3.9
0111	4.6
1000	5.4
1001	6.3
1010	7.3
1011	8.4
1100	9.8
1101	11.5
1110	13.8
1111	16.5

D[5:0]: duration setting of phase
D[5:4]: duration setting of phase 3
D[3:2]: duration setting of phase 2
D[1:0]: duration setting of phase 1

Bit[1:0]	Duration of Phase [Approximation]
00	10ms
01	20ms
10	30ms
11	40ms

0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control:
0	1		0	0	0	0	0	0	A_1	A_0		

A[1:0] :	Description
00	Normal Mode [POR]
01	Enter Deep Sleep Mode 1
11	Enter Deep Sleep Mode 2

After this command initiated, the chip will enter Deep Sleep Mode, BUSY pad will keep output high.
Remark:
To Exit Deep Sleep mode, User required to send HWRESET to the driver

0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence A[2:0] = 011 [POR] A [1:0] = ID[1:0] Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address. 00 –Y decrement, X decrement, 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR] A[2] = AM Set the direction in which the address counter is updated automatically after data are written to the RAM. AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.
0	1		0	0	0	0	0	A_2	A_1	A_0		
0	0	12	0	0	0	1	0	0	1	0	SW RESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode During operation, BUSY pad will output high. Note: RAM are unaffected by this command.
0	0	14	0	0	0	1	0	**1**	0	0	HV Ready Detection	HV ready detection A[7:0] = 00h [POR] The command required CLKEN=1 and ANALOGEN=1. Refer to Register 0x22 for detail. After this command initiated, HV Ready detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).
0	1		0	A_6	A_5	A_4	0	A_2	A_1	A_0		A[6:4]=n for cool down duration: 10ms x (n+1) A[2:0]=m for number of Cool Down Loop to detect. The max HV ready duration is 10ms x (n+1) x (m) HV ready detection will be trigger after each cool down time. The detection will be completed when HV is ready. For 1 shot HV ready detection, A[7:0] can be set as 00h.

0	0	15	0	0	0	1	0	1	0	1	VCI Detection	VCI Detection A[2:0] = 100 [POR] , Detect level at 2.3V A[2:0] : VCI level Detect A[2:0] VCI level 011 2.2V 100 2.3V 101 2.4V 110 2.5V 111 2.6V Other NA The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. After this command initiated, VCI detection starts. BUSY pad will output high during detection. The detection result can be read from the Status Bit Read (Command 0x2F).
0	1		0	0	0	0	0	A_2	A_1	A_0		
0	0	18	0	0	0	1	1	0	0	0	Temperature Sensor Control	Temperature Sensor Selection A[7:0] = 48h [POR], external temperatrure sensor A[7:0] = 80h Internal temperature sensor
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[11:0] = 7FFh [POR]
0	1		A_{11}	A_{10}	A_9	A_8	A_7	A_6	A_5	A_4		
0	1		A_3	A_2	A_1	A_0	0	0	0	0		
0	0	1B	0	0	0	1	1	0	1	1	Temperature Sensor Control (Read from temperature register)	Read from temperature register.
1	1		A_{11}	A_{10}	A_9	A_8	A_7	A_6	A_5	A_4		
1	1		A_3	A_2	A_1	A_0	0	0	0	0		
0	0	1C	0	0	0	1	1	1	0	0	Temperature Sensor Control (Write Command to External temperature sensor)	Write Command to External temperature sensor. A[7:0] = 00h [POR], B[7:0] = 00h [POR], C[7:0] = 00h [POR], A[7:6] A[7:6] Select no of byte to be sent 00 Address + pointer 01 Address + pointer + 1st parameter 10 Address + pointer + 1st parameter + 2nd pointer 11 Address A[5:0] – Pointer Setting B[7:0] – 1st parameter C[7:0] – 2nd parameter The command required CLKEN=1. Refer to Register 0x22 for detail. After this command initiated, Write Command to external temperature sensor starts. BUSY pad will output high during operation.
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
0	0	20	0	0	1	0	0	0	0	0	Master Activation	Activate Display Update Sequence The Display Update Sequence Option is located at R22h. BUSY pad will output high during operation. User should not interrupt this operation to avoid corruption of panel images.

0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	RAM content option for Display Update A[7:0] = 00h [POR] B[7:0] = 00h [POR] A[7:4] Red RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content A[3:0] BW RAM option 0000 Normal 0100 Bypass RAM content as 0 1000 Inverse RAM content B[7] Source Output Mode 0 Available Source from S0 to S175 1 Available Source from S8 to S167
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	0	0	0	0	0	0	0		

0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation A[7:0]= FFh (POR)
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

Operating sequence	Parameter (in Hex)
Enable clock signal	80
Disable clock signal	01
Enable clock signal → Enable Analog	C0
Disable Analog → Disable clock signal	03
Enable clock signal → Load LUT with DISPLAY Mode 1 → Disable clock signal	91
Enable clock signal → Load LUT with DISPLAY Mode 2 → Disable clock signal	99
Enable clock signal → Load temperature value → Load LUT with DISPLAY Mode 1 → Disable clock signal	B1
Enable clock signal → Load temperature value → Load LUT with DISPLAY Mode 2 → Disable clock signal	B9
Enable clock signal → Enable Analog → Display with DISPLAY Mode 1 → Disable Analog → Disable OSC	C7
Enable clock signal → Enable Analog → Display with DISPLAY Mode 2 → Disable Analog →Disable OSC	CF
Enable clock signal →Enable Analog → Load temperature value → DISPLAY with DISPLAY Mode 1 → Disable Analog → Disable OSC	F7
Enable clock signal →Enable Analog → Load temperature value → DISPLAY with DISPLAY Mode 2 → Disable Analog → Disable OSC	FF

0	0	24	0	0	1	0	0	1	0	0	Write RAM (Black White) / RAM 0x24	After this command, data entries will be written into the BW RAM until another command is written. Address pointers will advance accordingly For Write pixel: Content of Write RAM(BW) = 1 For Black pixel: Content of Write RAM(BW) = 0

Command Table												
R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	26	0	0	1	0	0	1	1	0	Write RAM (RED) / RAM 0x26	After this command, data entries will be written into the RED RAM until another command is written. Address pointers will advance accordingly. For Red pixel: Content of Write RAM(RED) = 1 For non-Red pixel [Black or White]: Content of Write RAM(RED) = 0
0	0	27	0	0	1	0	0	1	1	1	Read RAM	After this command, data read on the MCU bus will fetch data from RAM. According to parameter of Register 41h to select reading RAM0x24/ RAM0x26, until another command is written. Address pointers will advance accordingly. The 1st byte of data read is dummy data.
0	0	28	0	0	1	0	1	0	0	0	VCOM Sense	Enter VCOM sensing conditions and hold for duration defined in 29h before reading VCOM value. The sensed VCOM voltage is stored in register The command required CLKEN=1 and ANALOGEN=1 Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	29	0	0	1	0	1	0	0	1	VCOM Sense Duration	Stabling time between entering VCOM sensing mode and reading acquired. A[3:0] = 9h, duration = 10s. VCOM sense duration = (A[3:0]+1) sec
0	1		0	1	0	0	A_3	A_2	A_1	A_0		
0	0	2A	0	0	1	0	1	0	1	0	Program VCOM OTP	Program VCOM register into OTP The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	2B	0	0	1	0	1	0	1	1	Write Register for VCOM Control	This command is used to reduce glitch when ACVCOM toggle. Two data bytes D04h and D63h should be set for this command.
0	1		0	0	0	0	0	1	0	0		
0	1		0	1	1	0	0	0	1	1		

Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	2C	0	0	1	0	1	1	0	0	Write VCOM register	Write VCOM register from MCU interface A[7:0] = 00h [POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

A[7:0]	VCOM	A[7:0]	VCOM
08h	-0.2	44h	-1.7
0Ch	-0.3	48h	-1.8
10h	-0.4	4Ch	-1.9
14h	-0.5	50h	-2
18h	-0.6	54h	-2.1
1Ch	-0.7	58h	-2.2
20h	-0.8	5Ch	-2.3
24h	-0.9	60h	-2.4
28h	-1	64h	-2.5
2Ch	-1.1	68h	-2.6
30h	-1.2	6Ch	-2.7
34h	-1.3	70h	-2.8
38h	-1.4	74h	-2.9
3Ch	-1.5	78h	-3
40h	-1.6	Other	NA

0	0	2D	0	0	1	0	1	1	0	1	OTP Register Read for Display Option	Read Register for Display Option: A[7:0]: VCOM OTP Selection (Command 0x37, Byte A) B[7:0]: VCOM Register (Command 0x2C) C[7:0]~G[7:0]: Display Mode (Command 0x37, Byte B to Byte F) [5 bytes] H[7:0]~K[7:0]: Waveform Version (Command 0x37, Byte G to Byte J) [4 bytes]
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
1	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
1	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
1	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
1	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
1	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
1	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
1	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
1	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		
1	1		K_7	K_6	K_5	K_4	K_3	K_2	K_1	K_0		
0	0	2E	0	0	1	0	1	1	1	0	User ID Read	Read 10 Byte User ID stored in OTP: A[7:0]]~J[7:0]: UserID (R38, Byte A and Byte J) [10 bytes]
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
1	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
1	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
1	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
1	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
1	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
1	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
1	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
1	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
1	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		

0	0	2F	0	0	1	0	1	1	1	1	Status Bit Read	Read IC status Bit [POR 0x01] A[5]: HV Ready Detection flag [POR=0] 0: Ready 1: Not Ready A[4]: VCI Detection flag [POR=0] 0: Normal 1: VCI lower than the Detect level A[3]: [POR=0] A[2]: Busy flag [POR=0] 0: Normal 1: BUSY A[1:0]: Chip ID [POR=01] Remark: A[5] and A[4] status are not valid after RESET, they need to be initiated by command 0x14 and command 0x15 respectively.
1	1		0	0	A_5	A_4	0	0	A_1	A_0		

0	0	30	0	0	1	1	0	0	0	0	Program WS OTP	Program OTP of Waveform Setting The contents should be written into RAM before sending this command. The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	31	0	0	1	1	0	0	0	1	Load WS OTP	Load OTP of Waveform Setting The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU interface [153 bytes], which contains the content of VS[nX-LUTm], TP[nX], RP[n], SR[nXY], FR[n] and XON[nXY] Refer to Session 6.7 WAVEFORM SETTING
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		:	:	:	:	:	:	:	:		
0	1		.	..	.	.	.	.	.	.		
0	0	34	0	0	1	1	0	1	0	0	CRC calculation	CRC calculation command For details, please refer to SSD1680 application note. BUSY pad will output high during operation.
0	0	35	0	0	1	1	0	1	0	1	CRC Status Read	CRC Status Read A[15:0] is the CRC read out value
1	1		A_{15}	A_{14}	A_{13}	A_{12}	A_{11}	A_{10}	A_9	A_8		
1	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

0	0	36	0	0	1	1	0	1	1	0	Program OTP selection	Program OTP Selection according to the OTP Selection Control [R37h and R38h] The command required CLKEN=1. Refer to Register 0x22 for detail. BUSY pad will output high during operation.
0	0	37	0	0	1	1	0	1	1	1	Write Register for Display Option	Write Register for Display Option A[7] Spare VCOM OTP selection 0: Default [POR] 1: Spare B[7:0] Display Mode for WS[7:0] C[7:0] Display Mode for WS[15:8] D[7:0] Display Mode for WS[23:16] E[7:0] Display Mode for WS[31:24] F[3:0 Display Mode for WS[35:32] 0: Display Mode 1 1: Display Mode 2 F[6]: PingPong for Display Mode 2 0: RAM Ping-Pong disable [POR] 1: RAM Ping-Pong enable G[7:0]~J[7:0] module ID /waveform version. Remarks: 1) A[7:0]~J[7:0] can be stored in OTP 2) RAM Ping-Pong function is not support for Display Mode 1
0	1		A_7	0	0	0	0	0	0	0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
0	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
0	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
0	1		0	F_6	0	0	F_3	F_2	F_1	F_0		
0	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
0	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
0	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
0	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		

0	0	38	0	0	1	1	1	0	0	0	Write Register for User ID	Write Register for User ID A[7:0]~J[7:0]: UserID [10 bytes] Remarks: A[7:0]~J[7:0] can be stored in OTP
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		C_7	C_6	C_5	C_4	C_3	C_2	C_1	C_0		
0	1		D_7	D_6	D_5	D_4	D_3	D_2	D_1	D_0		
0	1		E_7	E_6	E_5	E_4	E_3	E_2	E_1	E_0		
0	1		F_7	F_6	F_5	F_4	F_3	F_2	F_1	F_0		
0	1		G_7	G_6	G_5	G_4	G_3	G_2	G_1	G_0		
0	1		H_7	H_6	H_5	H_4	H_3	H_2	H_1	H_0		
0	1		I_7	I_6	I_5	I_4	I_3	I_2	I_1	I_0		
0	1		J_7	J_6	J_5	J_4	J_3	J_2	J_1	J_0		
0	0	39	0	0	1	1	1	0	0	1	OTP program mode	OTP program mode A[1:0] = 00: Normal Mode [POR] A[1:0] = 11: Internal generated OTP programming voltage Remark: User is required to EXACTLY follow the reference code sequences
0	1		0	0	0	0	0	0	A_1	A_0		
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control	Select border waveform for VBD A[7:0] = C0h [POR], set VBD as HIZ. A [7:6] :Select VBD option
0	1		A_7	A_6	A_5	A_4	0	A_2	A_1	A_0		

A[7:6]	Select VBD as
00	GS Transition, Defined in A[2] and A[1:0]
01	Fix Level, Defined in A[5:4]
10	VCOM
11[POR]	HiZ

A [5:4] Fix Level Setting for VBD

A[5:4]	VBD level
00	VSS
01	VSH1
10	VSL
11	VSH2

A[2] GS Transition control

A[2]	GS Transition control
0	Follow LUT (Output VCOM @ RED)
1	Follow LUT

A [1:0] GS Transition setting for VBD

A[1:0]	VBD Transition
00	LUT0
01	LUT1
10	LUT2
11	LUT3

0	0	3F	0	0	1	1	1	1	1	1	End Option (EOPT)	Option for LUT end A[7:0]= 02h [POR]
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		

22h	Normal.
07h	Source output level keep previous output before power off

0	0	41	0	1	0	0	0	0	0	1	Read RAM Option	Read RAM Option A[0]= 0 [POR] 0 : Read RAM corresponding to RAM0x24 1 : Read RAM corresponding to RAM0x26
0	1		0	0	0	0	0	0	0	A_0		
0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit for RAM A[5:0]: XSA[5:0], XStart, POR = 00h B[5:0]: XEA[5:0], XEnd, POR = 15h
0	1		0	0	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	B_5	B_4	B_3	B_2	B_1	B_0		

0	0	45	0	1	0	0	0	1	0	1	Set Ram Y- address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit for RAM A[8:0]: YSA[8:0], YStart, POR = 000h B[8:0]: YEA[8:0], YEnd, POR = 127h
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	0	0	0	0	0	A_8		
0	1		B_7	B_6	B_5	B_4	B_3	B_2	B_1	B_0		
0	1		0	0	0	0	0	0	0	B_8		
0	0	46	0	1	0	0	0	1	1	0	Auto Write RED RAM for Regular Pattern	Auto Write RED RAM for Regular Pattern A[7:0] = 00h [POR] A[7]: The 1st step value, POR = 0 A[6:4]: Step Height, POR= 000 Step of alter RAM in Y-direction according to Gate A[6:4] Height A[6:4] Height 000 8 100 128 001 16 101 256 010 32 110 296 011 64 111 NA A[2:0]: Step Width, POR= 000 Step of alter RAM in X-direction according to Source A[2:0] Width A[2:0] Width 000 8 100 128 001 16 101 176 010 32 110 NA 011 64 111 NA BUSY pad will output high during operation.
0	1		A_7	A_6	A_5	A_4	0	A_2	A_1	A_0		
0	0	47	0	1	0	0	0	1	1	1	Auto Write B/W RAM for Regular Pattern	Auto Write B/W RAM for Regular Pattern A[7:0] = 00h [POR] A[7]: The 1st step value, POR = 0 A[6:4]: Step Height, POR= 000 Step of alter RAM in Y-direction according to Gate A[6:4] Height A[6:4] Height 000 8 100 128 001 16 101 256 010 32 110 296 011 64 111 NA A[2:0]: Step Width, POR= 000 Step of alter RAM in X-direction according to Source A[2:0] Width A[2:0] Width 000 8 100 128 001 16 101 176 010 32 110 NA 011 64 111 NA During operation, BUSY pad will output high.
0	1		A_7	A_6	A_5	A_4	0	A_2	A_1	A_0		

0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[5:0]: 00h [POR].
0	1		0	0	A_5	A_4	A_3	A_2	A_1	A_0		
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[8:0]: 000h [POR].
0	1		A_7	A_6	A_5	A_4	A_3	A_2	A_1	A_0		
0	1		0	0	0	0	0	0	0	A_8		
0	0	7F	0	1	1	1	1	1	1	1	NOP	This command is an empty command; it does not have any effect on the display module. However it can be used to terminate Frame Memory Write or Read Commands.

8. Optical Characteristics

Measurements are made with that the illumination is under an angle of 45 degree, the detection is perpendicular unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ.	Max	Units	Notes
R	White Reflectivity	White	30	35	-	%	8-1
CR	Contrast Ratio	Indoor	10	15	-		8-2
GN	2Grey Level	-		DS+(WS-DS)*n(m-1)			8-3
T update	Image update time	at 25 °C		12	-	sec	

Notes: 8-1. Luminance meter: Eye-One Pro Spectrophotometer.

8-2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.

8-3 WS: White state, DS: Dark state

9. Handling, Safety and Environment Requirements

Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact withelectrophoretic material, wash with water and soap.

Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases,which corrode electronic components. Disassembling the display module.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. Theglass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

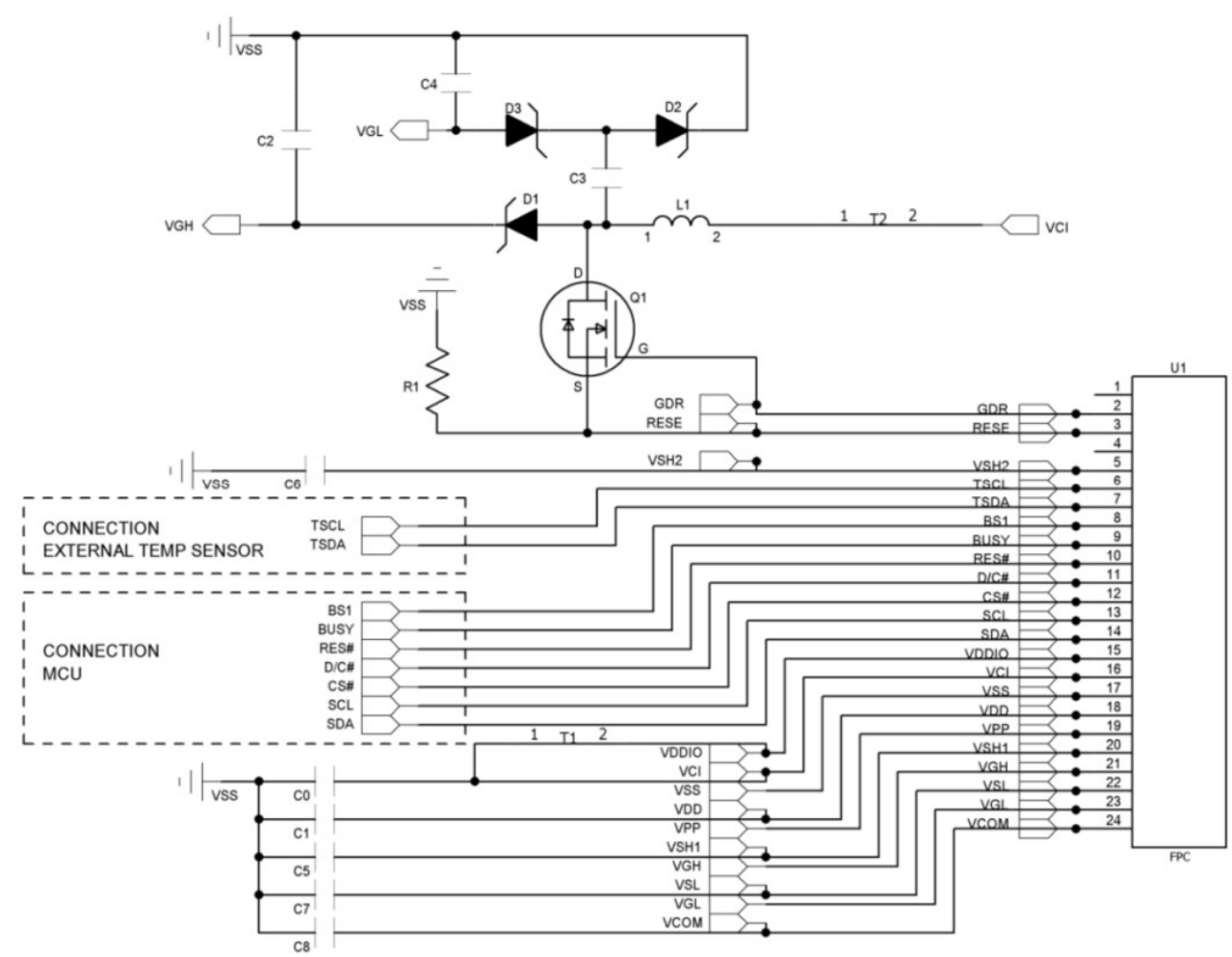
Data sheet status	
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System(IEC 134).Stress above one or more of the limiting values may cause permanent damage to the device.These are stress ratings only and operation of the device at these or at any other Conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

10. Reliability test

NO.	Test items	Test condition
1	Low-Temperature Storage	T = -25°C,240 h Test in white pattern
2	High-Temperature Storage	T=50ºC，RH=35%，240 h Test in white pattern
3	High-Temperature Operation	T=40ºC，RH=35%，240 h
4	Low-Temperature Operation	0ºC，240h
5	High-Temperature, High-Humidity Operation	T=40ºC，RH=90%，168 h
6	High Temperature, High Humidity Storage	T=50ºC，RH=90%,240 h Test in white pattern
7	Temperature Cycle	1cycle:[-25°C 30min]→[+70°C 30min]: 50cycles Test in white pattern
8	UV exposure Resistance	765W/m² for 168hrs,40 °C Test in white pattern
9	ESD Gun	Air+/-15KV;Contact+/-8KV (Test finished product shell, not display only) Air+/-8KV;Contact+/-6KV (Naked EPD display,no including IC and FPC area) Air+/-4KV;Contact+/-2KV (Naked EPD display,including IC and FPC area)

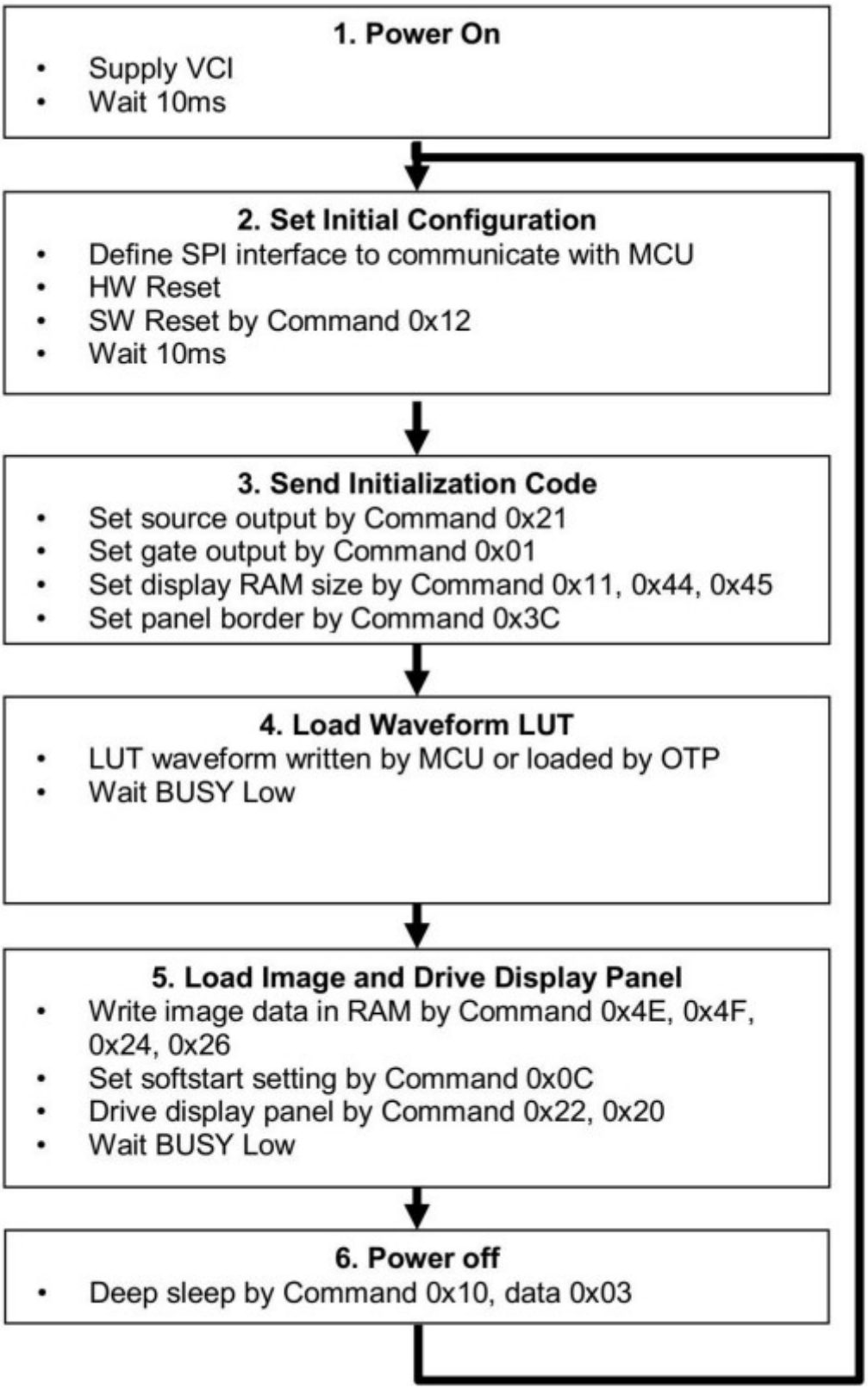
Note:Put in normal temperature for 1 hour after test finished, display performance is ok.

11. Typical Application Circuit with SPI Interface



Part Name	Value	Requirements/Reference Part
C0-C1	1uF	X5R/X7R; Voltage Rating : 6V or 25V
C2-C7	1uF	0402/0603/0805; X5R/X7R; Voltage Rating : 25V
C8	1uF	0402/0603/0805; X5R/X7R; Voltage Rating : 25V
R1	2.2 ohm	0402/0603/0805; 1% variation, ≥ 0.05W
D1-D3	Diode	MBR0530 1) Reverse DC voltage ≥ 30V 2) Io ≥ 500mA 3) Forward voltage ≤ 430mV
Q1	NMOS	Si1304BDL/NX3008NBK 1) Drain-Source breakdown voltage ≥ 30V 2) Vgs(th) = 0.9V (Typ), 1.3V (Max) 3) Rds on ≤ 2.1Ω @ Vgs = 2.5V
L1	47uH	CDRH2D18 / LDNP-470NC Io= 500mA (Max)
U1	0.5mm ZIF socket	24pins, 0.5mm pitch

12. Typical Operating Sequence



13. Inspection condition

13.1 Environment

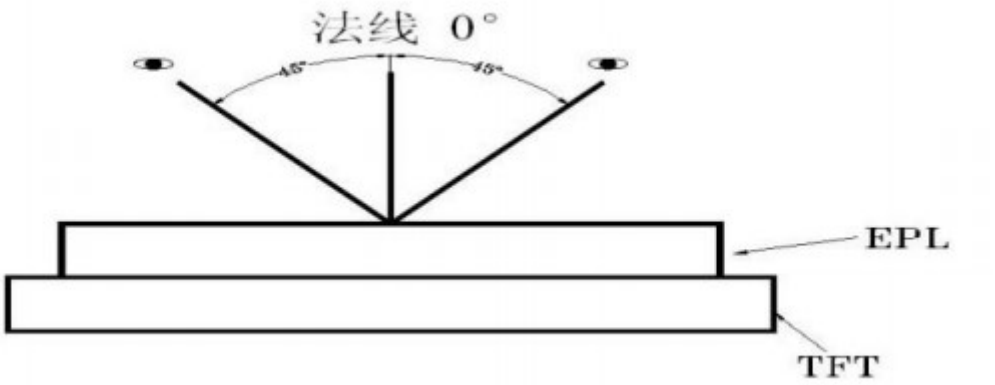
Temperature： 25±3 ℃

Humidity：55±10%RH

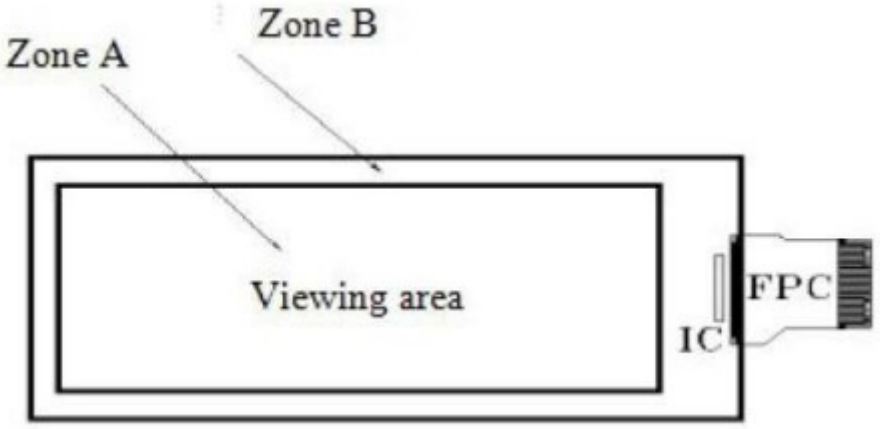
13.2 Illuminance

Brightness:1200～1500LUX; distance: 30CM; Angle: Relate 45°surround.

13.3 Inspect method

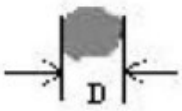
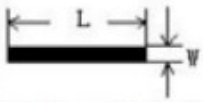


13.4 Display area

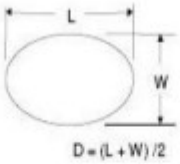
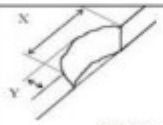
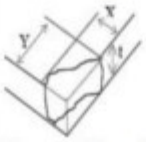
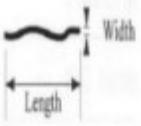


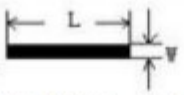
13.5 Inspection standard

13.5.1 Electric inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	Display	Clear display Display complete Display uniform	MA	Visual inspection	Zone A
2	Black/White spots	 D≤0.3mm，Allowed 0.3mm＜D≤0.5mm。N≤3， 0.5mm＜D Not Allow	MI		
3	Black/White spots (No switch)	 L≤1.0mm,W≤0.15mm negligible 1.0mm＜L≤4.0mm 0.15mm＜W≤0.5mm N≤4 allowable L＞4.0mm ,W＞0.5mm is not allowed		Visual/ Inspection card	
4	Ghost image	Allowed in switching process	MI	Visual inspection	
5	Flash dot / Multilateral	Flash points are allowed when switching screens Multilateral colors outside the frame are allowed for fixed screen time	MI	Visual/ Inspection card	Zone A Zone B
6	Segmented display	Selection segments are all displayed, and other segments are not displayed after the selection segment.	MA	Visual inspection	Zone A
7	Short circuit/ Circuit break/ Abnormal Display	Not Allow			

13.5.2 Appearance inspection standard

NO.	Item	Standard	Defect level	Method	Scope
1	B/W spots /Bubble/ Foreign bodies/ Dents	 D≤0.3mm，Allowed 0.3mm＜D≤0.5mm，N≤5 D＞0.5mm，Not Allow	MI	Visual inspection	Zone A
2	Glass crack	Not Allow	MA	Visual / Microscope	Zone A Zone B
3	\Dirty	Allowed if can be removed	MI		Zone A Zone B
4	Chips/Scratch/ Edge crown	 X≤3mm,Y≤0.5mm  2mm≤X or 2mm≤Y Allow  W≤0.1mm,L≤5mm, n≤ 2 Edge crown：X≤0.3mm，Y≤3mm	MI	Visual / Microscope	Zone A Zone B
5	TFT Cracks	 Not Allow	MA	Visual / Microscope	Zone A Zone B
6	Dirty/ foreign body	Allowed if can be removed/ allow	MI	Visual / Microscope	Zone A / Zone B
7	FPC broken/ FPC oxidation / scratch	  Not Allow	MA	Visual / Microscope	Zone B

8	B/W Line	 L≤1.0mm,W≤0.15mm negligible 1.0mm<L≤4.0mm 0.15mm<W≤0.5mm N≤4 allowable L>4.0mm ,W>0.5mm is not allowed	MI	Visual / Ruler	Zone B
9	TFT edge bulge /TFT chromatic aberration	TFT edge bulge: X≤3mm，Y≤0.3mm Allowed TFT chromatic aberration :Allowed	MI	Visual / Microscope	Zone A Zone B
10	Electrostatic point	D≤0.25mm, allow 0.25mm<D≤0.4mm ,n≤4 allow D>0.4mm is not allowed (n≤8 items are allowed within 5 mm in diameter)	MI	Visual / Microscope	Zone A
11	PCB damaged/ Poor welding/ Curl	PCB（Circuit area）damaged Not Allow PCB Poor welding Not Allow PCB Curl≤1%	MI	Visual / Ruler	Zone B
12	Edge glue height/ Edge glue bubble	Edge Adhesives H≤PS surface (Including protect film) Edge adhesives seep in≤1/2 Margin width Length excluding Edge adhesives bubble：bubble Width ≤1/2 Margin width；Length ≤0.5mm。n≤5	MI		
13	Protect film	Surface scratch but not effect protect function, Allow	MI	Visual Inspection	Zone B
14	Silicon glue	Thickness ≤ PS surface(With protect film): Full cover the IC; Shape: The width on the FPC ≤ 0.5mm (Front) The width on the FPC≤1.0mm (Back) smooth surface, No obvious raised.	MI	Visual Inspection	
15	Warp degree (TFT substrate)	 t≤1.5mm	MI	Ruler	
16	Color difference in COM area (Silver point area)	Allowed		Visual Inspection	

14. Packaging